



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-20
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST715C33R	HVW8*UL59J51	A	fina	2015-07-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	7.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	1.80 - 1.15 - 0.8	5	gull wing	
Comment	Package: SOT 323 5LDS, MD valid for CP:ST715C33R			

QueryList : ROHS directive 2011/65/EU _ July 2011

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
5 - Product(s) is obsolete, no information is available		false
6 - Product(s) is unknown, no information is available		false
Exemption Id.	Description	

QueryList : REACH-17th December 2014

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HVW8*UL59J51					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	1.030	mg	supplier	die	Silicon (Si)	7440-21-3		1.010	mg	980138	162143
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	4318	714
				supplier	metallization	Tungsten (W)	7440-33-7		0.004	mg	3454	571
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	864	143
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	6908	1143
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.004	mg	4318	714
Leadframe	Copper & its alloys	2.045	mg	supplier	alloy	Copper (Cu)	7440-50-8		1.970	mg	963462	316429
				supplier	alloy	Iron (Fe)	7439-89-6		0.045	mg	22184	7286
				supplier	alloy	Phosphorus (P)	12185-10-3		0.001	mg	435	143
				supplier	alloy	Zinc (Zn)	7440-66-6		0.003	mg	1305	429
				supplier	metallization	Nickel (Ni)	7440-02-0		0.023	mg	11309	3714
				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	870	286
Die attach	Other inorganic materials	0.021	mg	supplier	glue or tape	Gold (Au)	7440-57-5		0.001	mg	435	143
				supplier	glue or tape	Silver (Ag)	7440-22-4		0.014	mg	666667	2286
				supplier	glue or tape	methylene diacrylate	42594-17-2		0.005	mg	250000	857
				supplier	glue or tape	Dicyclopentenylxyethyl methacrylate	68586-19-6		0.001	mg	41667	143
Bonding wire	Precious metals	0.033	mg	supplier	glue or tape	Polymer of Polybutadiene + Anhydride	Proprietary		0.001	mg	41667	143
				supplier	wire	Copper (Cu)	7440-50-8		0.033	mg	1000000	5286
Encapsulation	Other inorganic materials	3.871	mg	supplier	mold compound	Silica, vitreous	60676-86-0		3.329	mg	860032	534571
				supplier	mold compound	phenolic resin	29690-82-2		0.116	mg	29878	18571
				supplier	mold compound	epoxy resin	25068-38-6		0.224	mg	57918	36000
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.194	mg	50103	31143
				supplier	mold compound	carbon black	1333-86-4		0.008	mg	2068	1286